



GE Energy

Functional Testing Specification

Parts & Repair Services
Louisville, KY

LOU-GED-DS200NATOG2A

Test Procedure for a DS200NATOG2A

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REV.	DESCRIPTION	SIGNATURE	REV. DATE
A	Initial release	Scott Cash	10-24-2011
B	Added comments pertaining to Ohmite resistors.	WG Chandler	6/14/2017

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DATE 10/24/2011	DATE	DATE	DATE 10/24/2011

<p>LOU-GED-DS200NATOG2A REV. A</p>	<p style="text-align: center;">g</p> <p style="text-align: center;">GE Energy <i>Parts & Repair Services</i> <i>Louisville, KY</i></p>	<p style="text-align: right;">Page 2 of 4</p>
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1. SCOPE

1.1 This is a functional testing procedure for DS200NATOG2A resistor board.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check board's electronic folder for more information

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires - broken, cracked, or loosely connected

4.2.1.2 Terminal strips / connectors - broken or cracked

4.2.1.3 Components - visually damaged

4.2.1.4 Capacitors - bloated or leaking

4.2.1.5 Solder joints - damaged or cold

4.2.1.6 Circuit board - burned or de-laminated

4.2.1.7 Printed wire runs / Traces - burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1	Fluke meter	Digital multimeter

6. Modifications/Upgrades

6.1 Check Orange Book for any modifications or upgrades.

7. Testing Process

7.1 Setup

7.1.1 There was an issue with cracked resistors on this board, check ECN's to make sure they don't need to be changed. Must change out EBG and Caddock resistors. EBG resistors can be identified by EBG, SSP32/F, 1M245B, XXXXX. **Use only Ohmite resistors.**

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7.2 Testing Procedure

7.2.1 Test the board per the following table.

From TP#	To TP#	Measurement
VAIN	E2	2.49 M ohm +\ - 10%
	E3	3.735 M ohm +\ - 10%
	JV-4	4.98 M ohm +\ - 10%
VBIN	E5	2.49 M ohm +\ - 10%
	E6	3.735 M ohm +\ - 10%
	JV-6	4.98 M ohm +\ - 10%
VCIN	E8	2.49 M ohm +\ - 10%
	E9	3.735 M ohm +\ - 10%
	JV-8	4.98 M ohm +\ - 10%
VDIN	E11	2.49 M ohm +\ - 10%
	E12	3.735 M ohm +\ - 10%
	JV-10	4.98 M ohm +\ - 10%
VEIN	E14	2.49 M ohm +\ - 10%
	E15	3.735 M ohm +\ - 10%
	JV-12	4.98 M ohm +\ - 10%
JV-1	JV-3	0 ohm +\ - 1.5 ohm
	JV-5	0 ohm +\ - 1.5 ohm
	JV-7	0 ohm +\ - 1.5 ohm
	JV-9	0 ohm +\ - 1.5 ohm
	JV-11	0 ohm +\ - 1.5 ohm
TPV	JV-13	0 ohm +\ - 1.5 ohm
	JV-19	0 ohm +\ - 1.5 ohm
	JV-14	0 ohm +\ - 1.5 ohm
JV-2	JV-20	0 ohm +\ - 1.5 ohm

7.2.2 Then verify that the MOV's are good.

7.3 ***TEST COMPLETE ***

8. Notes

8.1 None at this time.

9. Attachments

9.1 None at this time.